Dual Buffer with Open Drain Outputs

The NL27WZ07 is a high performance dual buffer with open drain outputs operating from a 1.65 to 5.5 V supply.

The internal circuit is composed of multiple stages, including an open drain output which provides the capability to set output switching level. This allows the NL27WZ07 to be used to interface 5 V circuits to circuits of any voltage between V_{CC} and 7.0 V using an external resistor and power supply.

Features

- Extremely High Speed: t_{PD} 2.3 ns (typical) at $V_{CC} = 5.0 \text{ V}$
- Designed for 1.65 V to 5.5 V V_{CC} Operation, CMOS compatible
- Over Voltage Tolerant Inputs
- $\bullet\,$ LVTTL Compatible Interface Capability with 5.0 V TTL Logic with $V_{CC}=3.0$ V
- LVCMOS Compatible
- 24 mA Output Sink Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18
- Pb-Free Packages are Available

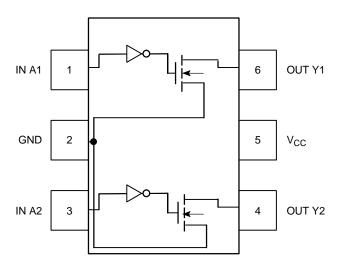


Figure 1. Pinout (Top View)

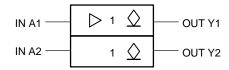


Figure 2. Logic Symbol



ON Semiconductor®

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MARKING DIAGRAMS



SC-88 DF SUFFIX CASE 419B



d = Date Code



TSOP-6 DT SUFFIX CASE 318G



Pin 1 d = Date Code

PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V _{CC}
6	OUT Y1

FUNCTION TABLE

Y Output
L
Z

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol		Characteristics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \le V_1 \le +7.0$	V
Vo	DC Output Voltage	Output in Z or LOW State (Note 1)	$-0.5 \le V_{O} \le 7.0$	V
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
lok	DC Output Diode Current	V _O < GND	-50	mA
Io	DC Output Sink Current		±50	mA
Icc	DC Supply Current per Supp	ly Pin	±100	mA
I _{GND}	DC Ground Current per Grou	ınd Pin	±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
P _D	Power Dissipation in Still Air	SC-88, TSOP-6	200	mW
θ_{JA}	Thermal Resistance	SC-88, TSOP-6	333	°C/W
TL	Lead Temperature, 1 mm from	m case for 10 s	260	°C
TJ	Junction Temperature under	Bias	+150	°C
I _{Latch-Up}	Latch-Up Performance	Above V _{CC} and Below GND at 85°C (Note 5)	±500	mA
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Classification	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 N/A	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- I_O absolute maximum rating must be observed.
 Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
 Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A
- 5. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	(Z or LOW State)	0	5.5	V
T _A	Operating Free-Air Temperature		-40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T,	4 = 25°	С	-40°C ≤1	T _A ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.75 V _{CC}			0.75 V _{CC} 0.75 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.3 V _{CC} 0.3 V _{CC}		0.3 V _{CC} 0.3 V _{CC}	V
I _{LKG}	Z-State Output Leakage Current	$V_{IN} = V_{IL}$ $V_{OUT} = V_{CC}$ or GND	2.3 to 5.5			±5.0		±10.0	μΑ
V _{OL}	Low-Level Output Voltage	I _{OL} = 100 μA	1.65 to 5.5		0.0	0.1		0.1	V
	$V_{IN} = V_{IL}$	I _{OL} = 4 mA	1.65		0.08	0.24		0.24	
		I _{OL} = 8 mA	2.3		0.20	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5		0.42	0.55		0.55	
I _{IN}	Input Leakage Current	V _{IN} or V _{OUT} = V _{CC} or GND	0 to 5.5			± 0.1		±1.0	μΑ
I _{OFF}	Power Off-Output Leakage Current	V _{OUT} = 5.5 V	0			1		10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μА

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

				T _A = 25°C		-40°C ≤1			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PZL}	Propagation Delay	$R_{L} = R_1 = 5000 \Omega, C_L = 15 pF$	1.8 ± 0.15	1.8	5.3	11.5	1.8	12.0	ns
	(Figure 3 and 4)	$R_{L} = R_1 = 500 \Omega, C_L = 50 pF$	2.5 ± 0.2	1.2	3.7	5.8	1.2	6.4	
			3.3 ± 0.3	0.8	2.9	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	2.3	3.5	0.5	3.9	
t _{PLZ}	Propagation Delay	$R_{L} = R_1 = 5000 \Omega, C_L = 15 pF$	1.8 ± 0.15	1.8	5.3	11.5	1.8	12.0	ns
	(Figure 3 and 4)	$R_{L} = R_1 = 500 \Omega, C_L = 50 pF$	2.5 ± 0.2	1.2	2.8	5.8	1.2	6.4	
			3.3 ± 0.3	0.8	2.1	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	1.4	3.5	0.5	3.9	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	4.0	pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

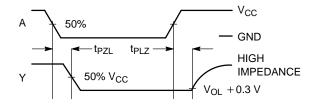
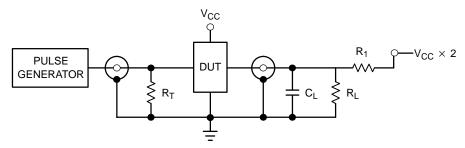


Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

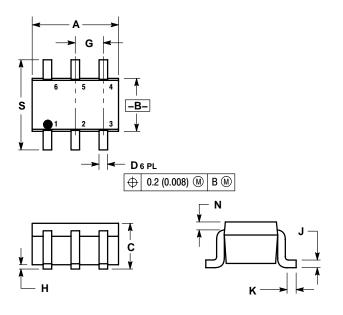
ORDERING INFORMATION

			Devi	ce Nomenclat	ure				
Device	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type (Name/SOT#/ Common Name)	Shipping [†]
NL27WZ07DFT2	NL	2	7	WZ	07	DF	T2	SC-88 / SOT-363 / SC-70	178 mm (7") 3000 Unit
NL27WZ07DFT2G	NL	2	7	WZ	07	DF	T2	SC-88 / SOT-363 / SC-70 (Pb-Free)	178 mm (7") 3000 Unit
NL27WZ07DTT1	NL	2	7	WZ	07	DT	T1	TSOP-6 / SOT-23 / SC-59	178 mm (7") 3000 Unit
NL27WZ07DTT1G	NL	2	7	WZ	07	DT	T1	TSOP-6 / SOT-23 / SC-59 (Pb-Free)	178 mm (7") 3000 Unit

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

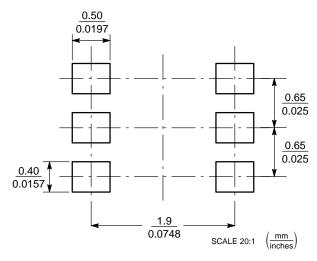
SC-88 (SOT-363) **DF SUFFIX** CASE 419B-02 **ISSUE T**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

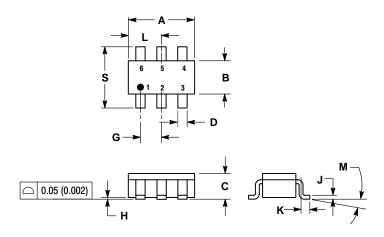
SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-6 **DT SUFFIX** CASE 318G-02 ISSUE K



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
М	0	10	0	10
S	2.50	3.00	0.0985	0.1181

SOLDERING FOOTPRINT*

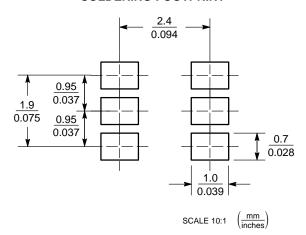


Figure 5. TSOP-6

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.